

## CLAIMS:

1. A test device for testing an integrated circuit comprising a plurality of contacts, called test circuit, intended to be tested with the aid of a test printed circuit, called main circuit, the device comprising an insulating membrane of a soft material having two  
5 opposite surfaces covered by two conductive layers interconnected by connection means and intended to come into contact with the test circuit and the main circuit respectively, under the influence of a pressing force exerted during the test between the test circuit and the main circuit deforming the test device, protrusions being arranged on at least one of said layers according to a predefined pattern as a function of said contacts of the test circuit, so as to  
10 ensure a contact quality between said layer and the test circuit or the main circuit in contact with said layer, under the influence of said pressing force.
2. A device as claimed in claim 1, in which said connection means are provided by metallized holes passing through said membrane and the two layers.  
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3. A device as claimed in claim 1, in which the device has a thickness less than or equal to 0.4 millimeter.
4. A device as claimed in claim 1, in which the membrane has a thickness less  
20 than or equal to 0.1 millimeter.
5. A device as claimed in claim 1, in which the protrusions have a height larger than or equal to 45 micrometers.
- 25 6. A device as claimed in claim 1, in which the protrusions have a diameter relative to the surface of said contacts.
7. A device as claimed in claim 1, in which the membrane is made of Kapton.

8. A test device as claimed in claim 1, in which the protrusions are arranged in pairs on each of the two layers, each element of the pair being situated on an opposite layer on either side of the connection means, so as to perform a change of the soft membrane under the influence of said pressing force.

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9. A test method comprising the delivery of an integrated circuit called test circuit in a given housing from a set of different types of housings, intended to be tested by a test circuit, called main circuit, and a set of test devices as claimed in claim 1 corresponding to said set of housings adapted to said test circuit as a function of each type of housing considered.

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10. A test method as claimed in claim 9, in which each test device comprises on a first surface, called standard surface, a standard conductive layer adapted to the main circuit and on a second surface, called specific surface, a specific conductive layer adapted to a predefined type of housing.

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